# **Small Signal MOSFET**

# 30 V, 154 mA, Single, N-Channel, Gate **ESD Protection, SC-75**

#### **Features**

- Low Gate Charge for Fast Switching
- Small 1.6 x 1.6 mm Footprint
- ESD Protected Gate
- Pb-Free Package is Available

#### **Applications**

- Power Management Load Switch
- Level Shift
- Portable Applications such as Cell Phones, Media Players, Digital Cameras, PDA's, Video Games, Hand-Held Computers, etc.

#### **MAXIMUM RATINGS** (T<sub>J</sub> = 25°C unless otherwise noted)

| Paramo  | Symbol                                      | Value           | Unit |    |
|---|---|-----------------|------|----|
| Drain-to-Source Voltage   |   | $V_{DSS}$       | 30   | V  |
| Gate-to-Source Voltage  |   | $V_{GS}$        | ±10  | V  |
| Continuous Drain<br>Current (Note 1)                              | Steady State = 25°C                         | I <sub>D</sub>  | 154  | mA |
| Power Dissipation (Note 1)  | Steady State = 25°C                         | P <sub>D</sub>  | 300  | mW |
| Pulsed Drain Current  | Pulsed Drain Current t <sub>P</sub> ≤ 10 μs |                 | 618  | mA |
| Operating Junction and S  | T <sub>J</sub> ,<br>T <sub>STG</sub>        | -55 to<br>150   | °C   |    |
| Continuous Source Current (Body Diode)                            |   | I <sub>SD</sub> | 154  | mA |
| Lead Temperature for Soldering Purposes (1/8" from case for 10 s) |   | TL              | 260  | °C |

#### THERMAL RESISTANCE RATINGS

| Parameter                                   | Symbol          | Max | Unit |
|---|-----------------|-----|------|
| Junction-to-Ambient - Steady State (Note 1) | $R_{\theta JA}$ | 416 | °C/W |

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

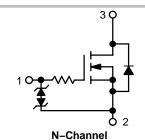
1. Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).



# ON Semiconductor®

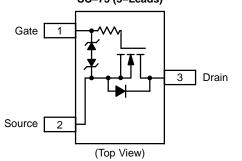
## http://onsemi.com

| V <sub>(BR)DSS</sub> | R <sub>DS(on)</sub><br>Typ @ V <sub>GS</sub> | I <sub>D</sub> MAX<br>(Note 1) |
|----------------------|--|--------------------------------|
| 20.1/                | 1.4 Ω @ 4.5 V                                | 151 m A                        |
| 30 V                 | 2.3 Ω @ 2.5 V                                | 154 mA                         |

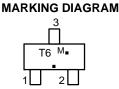


# **PIN CONNECTIONS**

SC-75 (3-Leads)







= Specific Device Code

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

| Device      | Package            | Shipping†        |
|-------------|--------------------|------------------|
| NTA7002NT1  | SC-75              | 3000 Tape & Reel |
| NTA7002NT1G | SC-75<br>(Pb-Free) | 3000 Tape & Reel |

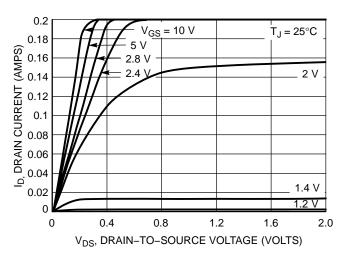
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise specified)

| Parameter                          | Symbol               | Test Condition   | Min | Тур  | Max  | Unit |
|------------------------------------|----------------------|--|-----|------|------|------|
| OFF CHARACTERISTICS                | _                    |  | •   | •    | •    |      |
| Drain-to-Source Breakdown Voltage  | V <sub>(BR)DSS</sub> | $V_{GS} = 0 \text{ V}, I_{D} = 100 \mu\text{A}$                                | 30  |      |      | V    |
| Zero Gate Voltage Drain Current    | I <sub>DSS</sub>     | V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 30 V                                  |     |      | 1.0  | μΑ   |
| Zero Gate Voltage Drain Current    | I <sub>DSS</sub>     | $V_{GS} = 0 \text{ V}, V_{DS} = 20 \text{ V}, $<br>$T = 85 ^{\circ}\text{C}$   |     |      | 1.0  | μΑ   |
| Gate-to-Source Leakage Current     | I <sub>GSS</sub>     | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 10 \text{ V}$                              |     |      | ±25  | μΑ   |
| Gate-to-Source Leakage Current     | I <sub>GSS</sub>     | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 5 \text{ V}$                               |     |      | ±1.0 | μΑ   |
| Gate-to-Source Leakage Current     | I <sub>GSS</sub>     | $V_{DS} = 0 \text{ V, } V_{GS} = \pm 5 \text{ V}$<br>$T = 85 ^{\circ}\text{C}$ |     |      | ±1.0 | μΑ   |
| ON CHARACTERISTICS (Note 2)        | •                    |  | •   | •    | •    |      |
| Gate Threshold Voltage             | V <sub>GS(TH)</sub>  | $V_{DS} = V_{GS}, I_{D} = 100 \mu A$   | 0.5 | 1.0  | 1.5  | V    |
| Drain-to-Source On Resistance      | R <sub>DS(on)</sub>  | $V_{GS} = 4.5 \text{ V}, I_D = 154 \text{ mA}$                                 |     | 1.4  | 7.0  | Ω    |
|                                    |                      | $V_{GS} = 2.5 \text{ V}, I_D = 154 \text{ mA}$                                 |     | 2.3  | 7.5  |      |
| Forward Transconductance           | 9FS                  | $V_{DS} = 3 \text{ V}, I_{D} = 154 \text{ mA}$                                 |     | 80   |      | mS   |
| CAPACITANCES                       |                      |  |     |      |      |      |
| Input Capacitance                  | C <sub>ISS</sub>     |  |     | 11.5 |      |      |
| Output Capacitance                 | C <sub>OSS</sub>     | $V_{DS} = 5.0 \text{ V, f} = 1 \text{ MHz,}$<br>$V_{GS} = 0 \text{ V}$         |     | 10   |      | pF   |
| Reverse Transfer Capacitance       | C <sub>RSS</sub>     | 100 - 1  |     | 3.5  |      |      |
| SWITCHING CHARACTERISTICS (Note 3) |                      |  |     |      |      |      |
| Turn-On Delay Time                 | t <sub>d(ON)</sub>   | V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 5.0 V,                              |     | 13   |      | ns   |
| Rise Time                          | t <sub>r</sub>       |  |     | 15   |      |      |
| Turn-Off Delay Time                | t <sub>d(OFF)</sub>  | $I_D = 75 \text{ mA}, R_G = 10 \Omega$   |     | 98   |      | ns   |
| Fall Time                          | t <sub>f</sub>       |  |     | 60   |      |      |
| Drain-Source Diode Characteristics |                      |  | _   |      |      |      |
| Forward Diode Voltage              | $V_{SD}$             | $V_{GS} = 0 \text{ V}, I_{S} = 0.154 \text{ mA}$                               |     | 0.77 | 0.9  | V    |

Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
Switching characteristics are independent of operating junction temperatures.

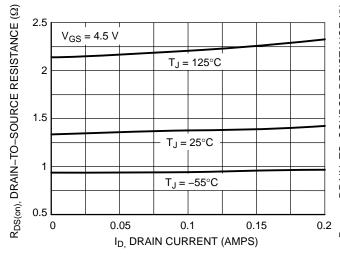
#### **TYPICAL PERFORMANCE CURVES**



0.2 V<sub>DS</sub> = 5 V 0.16 0.12 0.08 T<sub>J</sub> = 125°C T<sub>J</sub> = -55°C 0.6 0.8 1 1.2 1.4 1.6 1.8 2 V<sub>GS</sub>, GATE-TO-SOURCE VOLTAGE (VOLTS)

Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



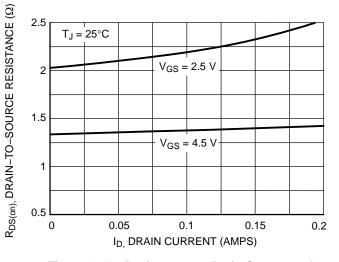
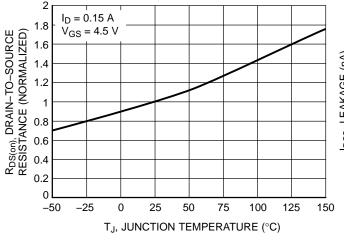


Figure 3. On–Resistance vs. Drain Current and Temperature

Figure 4. On–Resistance vs. Drain Current and Gate Voltage



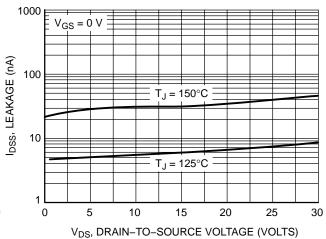
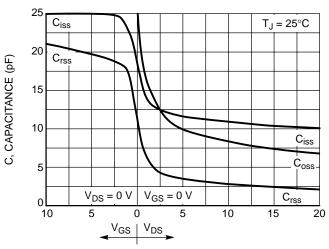
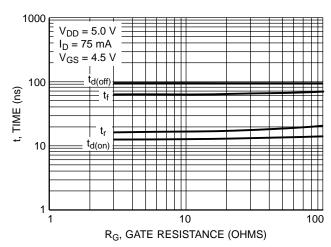


Figure 5. On–Resistance Variation with Temperature

Figure 6. Drain-to-Source Leakage Current vs. Voltage

# **TYPICAL PERFORMANCE CURVES**





GATE-TO-SOURCE OR DRAIN-TO-SOURCE VOLTAGE (VOLTS)

Figure 7. Capacitance Variation

Figure 8. Resistive Switching Time Variation vs. Gate Resistance

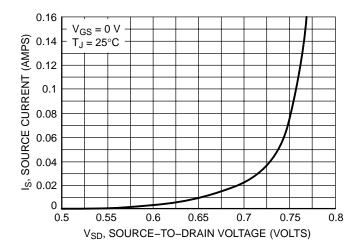
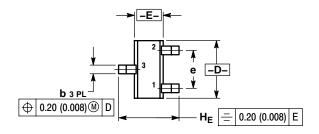
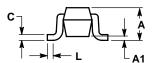


Figure 9. Diode Forward Voltage vs. Current

## **PACKAGE DIMENSIONS**

SC-75 / SOT-416 CASE 463-01 ISSUE F



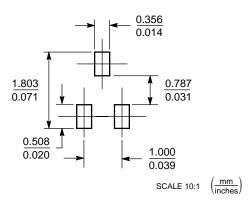


- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.

|     | MILLIMETERS |      |      | INCHES |          |       |  |
|-----|-------------|------|------|--------|----------|-------|--|
| DIM | MIN         | NOM  | MAX  | MIN    | NOM      | MAX   |  |
| Α   | 0.70        | 0.80 | 0.90 | 0.027  | 0.031    | 0.035 |  |
| A1  | 0.00        | 0.05 | 0.10 | 0.000  | 0.002    | 0.004 |  |
| b   | 0.15        | 0.20 | 0.30 | 0.006  | 0.008    | 0.012 |  |
| С   | 0.10        | 0.15 | 0.25 | 0.004  | 0.006    | 0.010 |  |
| D   | 1.55        | 1.60 | 1.65 | 0.059  | 0.063    | 0.067 |  |
| E   | 0.70        | 0.80 | 0.90 | 0.027  | 0.031    | 0.035 |  |
| е   | 1.00 BSC    |      |      | C      | 0.04 BSC |       |  |
| L   | 0.10        | 0.15 | 0.20 | 0.004  | 0.006    | 0.008 |  |
| HE  | 1.50        | 1.60 | 1.70 | 0.061  | 0.063    | 0.065 |  |

STYLE 5: PIN 1. GATE 2. SOURCE 3. DRAIN

# **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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